

Low Voltage 4 Ω Dual SPST Switches

ADG721/ADG722/ADG723

FEATURES

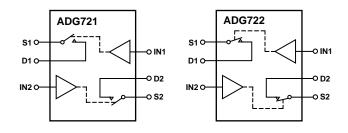
+1.8 V to +5.5 V Single Supply 4 Ω (Max) On Resistance Low On-Resistance Flatness -3 dB Bandwidth >200 MHz Rail-to-Rail Operation 8-Lead μ SOIC Package Fast Switching Times

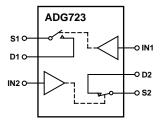
 t_{ON} 20 ns t_{OFF} 10 ns

Low Power Consumption (<0.1 μ W) TTL/CMOS Compatible

APPLICATIONS
Battery Powered Systems
Communication Systems
Sample Hold Systems
Audio Signal Routing
Video Switching
Mechanical Reed Relay Replacement

FUNCTIONAL BLOCK DIAGRAMS





SWITCHES SHOWN FOR A LOGIC "0" INPUT

GENERAL DESCRIPTION

The ADG721, ADG722 and ADG723 are monolithic CMOS SPST switches. These switches are designed on an advanced submicron process that provides low power dissipation yet gives high switching speed, low On resistance and low leakage currents.

The ADG721, ADG722 and ADG723 are designed to operate from a single +1.8 V to +5.5 V supply, making them ideal for use in battery powered instruments and with the new generation of DACs and ADCs from Analog Devices.

The ADG721, ADG722 and ADG723 contain two independent single-pole/single-throw (SPST) switches. The ADG721 and ADG722 differ only in that both switches are normally open and normally closed respectively. While in the ADG723, Switch 1 is normally open and Switch 2 is normally closed.

Each switch of the ADG721, ADG722 and ADG723 conducts equally well in both directions when on. The ADG723 exhibits break-before-make switching action.

PRODUCT HIGHLIGHTS

- 1. +1.8 V to +5.5 V Single Supply Operation. The ADG721, ADG722 and ADG723 offers high performance, including low on resistance and fast switching times and is fully specified and guaranteed with +3 V and +5 V supply rails.
- 2. Very Low R_{ON} (4 Ω max at 5 V, 10 Ω max at 3 V). At 1.8 V operation, R_{ON} is typically 40 Ω over the temperature range.
- 3. Low On-Resistance Flatness.
- 4. -3 dB Bandwidth >200 MHz.
- Low Power Dissipation. CMOS construction ensures low power dissipation.
- 6. Fast t_{ON}/t_{OFF}.
- 7. 8-Lead μSOIC.

	B Version			
Parameter	+25°C	-40°C to +85°C	Units	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		0 V to V _{DD}	V	
On Resistance (R _{ON})	4	5	Ω max	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA},$ Test Circuit 1
On Resistance Match Between				
Channels (ΔR_{ON})	0.3	1.0	Ω typ Ω max	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$
On-Resistance Flatness (R _{FLAT(ON)})	0.85	1.5	Ω typ Ω max	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$
LEAKAGE CURRENTS				$V_{DD} = +5.5 \text{ V}$
Source OFF Leakage I _S (OFF)	±0.01		nA typ	$V_S = 4.5 \text{ V/1 V}, V_D = 1 \text{ V/4.5 V}$
2 3 ()	±0.25	±0.35	nA max	Test Circuit 2
Drain OFF Leakage I _D (OFF)	±0.01		nA typ	$V_S = 4.5 \text{ V/1 V}, V_D = 1 \text{ V/4.5 V}$
	±0.25	±0.35	nA max	Test Circuit 2
Channel ON Leakage ID, IS (ON)	±0.01		nA typ	$V_S = V_D = 1 \text{ V}, \text{ or } V_S = V_D = 4.5 \text{ V}$
0 B, 0 ()	±0.25	±0.35	nA max	Test Circuit 3
DIGITAL INPUTS				
Input High Voltage, V _{INH}		2.4	V min	
Input Low Voltage, V _{INL}		0.8	V max	
Input Current		0.0	VIIIAA	
I _{INL} or I _{INH}	0.005		μA typ	$V_{IN} = V_{INI}$ or V_{INH}
INL OF TINH	0.005	±0.1	μΑ max	VIN - VINL OI VINH
DYNAMIC CHARACTERISTICS ²				
	14		no trm	$R_{L} = 300 \Omega, C_{L} = 35 pF$
t_{ON}	14	20	ns typ	$V_S = 3 \text{ V}, \text{ Test Circuit 4}$
+	6	20	ns max	$R_L = 300 \Omega$, $C_L = 35 pF$
$t_{ m OFF}$	0	10	ns typ ns max	$V_S = 3 \text{ V}$, Test Circuit 4
Break-Before-Make Time Delay, t _D	7	10		$R_L = 300 \Omega$, $C_L = 35 pF$,
(ADG723 Only)	'	1	ns typ ns min	$V_{S1} = V_{S2} = 3 \text{ V, Test Circuit 5}$
Charge Injection	2	1	pC typ	$V_S = V_{S2} = 3 \text{ V}$, rest circuit S $V_S = 2 \text{ V}$; $R_S = 0 \Omega$, $C_L = 1 \text{ nF}$, Test Circuit S
Off Isolation	-60		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 10 MHz$
011 10011111011	-80		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$, Test Circuit 7
Channel-to-Channel Crosstalk	-77		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 10 MHz$
	-97		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$, Test Circuit 8
Bandwidth -3 dB	200		MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$, Test Circuit 9
C _S (OFF)	7		pF typ	E - J - E - F J - ST - E- ST -
C _D (OFF)	7		pF typ	
$C_D, C_S (ON)$	18		pF typ	
POWER REQUIREMENTS				$V_{\rm DD}$ = +5.5 V Digital Inputs = 0 V or 5 V
T	0.001		μA typ	
I_{DD}	0.001	1.0	μΑ typ μΑ max	
		1.0	μα IIIax	

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NOTES

¹Temperature ranges are as follows: B Version, -40°C to +85°C.

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

 $\label{eq:continuous} \textbf{SPECIFICATIONS}^{1}(\textbf{V}_{DD} = +3~\textbf{V} \pm~10\%,~\textbf{GND} = 0~\textbf{V}.~~\textbf{All specifications}~-40^{\circ}\text{C to}~+85^{\circ}\text{C},~\textbf{unless otherwise noted.})$

	B Version				
_		-40°C to			
Parameter	+25°C	+85°C	Units	Test Conditions/Comments	
ANALOG SWITCH					
Analog Signal Range		0 V to V _{DD}	V		
On Resistance (R _{ON})	6.5		Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$	
V 610		10	Ω max	Test Circuit 1	
On Resistance Match Between					
Channels (ΔR_{ON})	0.3		Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = -10 \text{ mA}$	
olv		1.0	Ω max		
On-Resistance Flatness (R _{FLAT(ON)})		3.5	Ω typ	$V_{S} = 0 \text{ V to } V_{DD}, I_{S} = -10 \text{ mA}$	
			J1		
LEAKAGE CURRENTS				$V_{DD} = +3.3 \text{ V}$	
Source OFF Leakage I _S (OFF)	±0.01		nA typ	$V_S = 3 \text{ V/1 V}, V_D = 1 \text{ V/3 V}$	
	±0.25	±0.35	nA max	Test Circuit 2	
Drain OFF Leakage I _D (OFF)	± 0.01		nA typ	$V_S = 3 \text{ V/1 V}, V_D = 1 \text{ V/3 V}$	
	±0.25	±0.35	nA max	Test Circuit 2	
Channel ON Leakage I_D , I_S (ON)	± 0.01		nA typ	$V_S = V_D = 1 \text{ V, or } 3 \text{ V}$	
	±0.25	±0.35	nA max	Test Circuit 3	
DIGITAL INPUTS					
Input High Voltage, V _{INH}		2.0	V min		
Input Low Voltage, V _{INI}		0.4	V max		
Input Current		0.4	v IIIax		
I _{INL} or I _{INH}	0.005		u A tre	$V_{IN} = V_{INI}$ or V_{INH}	
I _{INL} of I _{INH}	0.003	±0.1	μA typ	VIN - VINL OI VINH	
		±0.1	μA max		
DYNAMIC CHARACTERISTICS ²					
t_{ON}	16		ns typ	$R_L = 300 \Omega, C_L = 35 pF$	
		24	ns max	$V_S = 2 V$, Test Circuit 4	
t _{OFF}	7		ns typ	$R_L = 300 \Omega, C_L = 35 pF$	
		11	ns max	$V_S = 2 V$, Test Circuit 4	
Break-Before-Make Time Delay, t _D	7		ns typ	$R_L = 300 \Omega, C_L = 35 pF,$	
(ADG723 Only)		1	ns min	$V_{S1} = V_{S2} = 2 \text{ V}$, Test Circuit 5	
Charge Injection	2		pC typ	$V_S = 1.5 \text{ V}; R_S = 0 \Omega, C_L = 1 \text{ nF},$	
,			1 71	Test Circuit 6	
Off Isolation	-60		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 10 MHz$	
	-80		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$,	
			J F	Test Circuit 7	
Channel-to-Channel Crosstalk	-77		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 10 MHz$	
	-97		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$,	
	'.		'JP	Test Circuit 8	
Bandwidth –3 dB	200		MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$,	
Danamani Jab	200		TTILL LYP	Test Circuit 9	
C _s (OFF)	7		pF typ	1 cot Official y	
$C_S(OFF)$ $C_D(OFF)$	7		pF typ		
$C_D(OPP)$ $C_D, C_S(ON)$	18				
	10		pF typ		
POWER REQUIREMENTS				$V_{DD} = +3.3 \text{ V}$	
				Digital Inputs = 0 V or 3 V	
I_{DD}	0.001		μA typ		
		1.0	μA max		

NOTES

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 $^{^{1}}Temperature$ ranges are as follows: B Version, $-40^{\circ}C$ to +85°C.

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS1

$(T_A = +25^{\circ}C \text{ unless otherwise noted})$
V _{DD} to GND
Analog, Digital Inputs ² -0.3 V to $V_{DD} + 0.3 \text{ V}$ or
30 mA, Whichever Occurs First
Continuous Current, S or D
Operating Temperature Range
Industrial (B Version)40°C to +85°C
Storage Temperature Range65°C to +150°C
Junction Temperature +150°C
μSOIC Package, Power Dissipation 450 mW
θ_{JA} Thermal Impedance
θ_{JC} Thermal Impedance
Lead Temperature, Soldering
Vapor Phase (60 sec) +215°C
Infrared (15 sec) +220°C
ESD

NOTES

Table I. Truth Table (ADG721/ADG722)

ADG721 In	ADG722 In	Switch Condition	
0	1	OFF	
1	0	ON	

Table II. Truth Table (ADG723)

Logic	Switch 1	Switch 2	
0	OFF	ON	
1	ON	OFF	

TERMINOLOGY

Most Positive Power Supply Potential.			
Ground (0 V) Reference.			
Source Terminal. May be an input or output.			
Drain Terminal. May be an input or output.			
Logic Control Input.			
Ohmic resistance between D and S.			
On resistance match between any two channels			
i.e., R_{ON} max – R_{ON} min.			
Flatness is defined as the difference between the			
maximum and minimum value of on resistance as			
measured over the specified analog signal range.			
Source leakage current with the switch "OFF."			
Drain leakage current with the switch "OFF."			
Channel leakage current with the switch "ON."			
Analog voltage on terminals D, S.			
"OFF" Switch Source Capacitance.			
"OFF" Switch Drain Capacitance.			
"ON" Switch Capacitance.			
Delay between applying the digital control input and the output switching on.			
Delay between applying the digital control input			
and the output switching off. "OFF" time or "ON" time measured between the			
90% points of both switches, When switching			
from one address state to another. (ADG723 Only)			
A measure of unwanted signal which is coupled			
through from one channel to another as a result			
of parasitic capacitance.			
A measure of unwanted signal coupling through			
an "OFF" switch.			
A measure of the glitch impulse transferred			
during switching.			

PIN CONFIGURATION 8-Lead µSOIC (RM-8)

IN2 3 TOP VIEW 6 I

ORDERING GUIDE

Model	Temperature Range	Brand*	Package Description	Package Option
ADG721BRM	-40°C to +85°C	S6B	μSOIC	RM-8
ADG722BRM	-40°C to +85°C	S7B	μSOIC	RM-8
ADG723BRM	-40°C to +85°C	S8B	μSOIC	RM-8

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CAUTION_

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG721/ADG722/ADG723 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

²Overvoltages at IN, S or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

 $[\]star$ Brand = Due to package size limitations, these three characters represent the part number.

Typical Performance Characteristics—ADG721/ADG722/ADG723

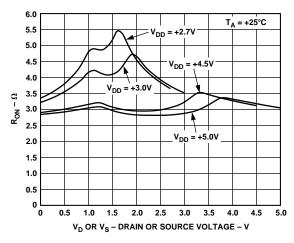


Figure 1. On Resistance as a Function of V_D (V_S) Single Supplies

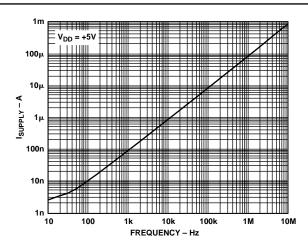


Figure 4. Supply Current vs. Input Switching Frequency

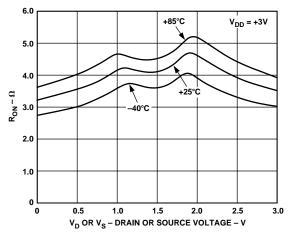


Figure 2. On Resistance as a Function of V_D (V_S) for Different Temperatures $V_{DD} = +3 \text{ V}$

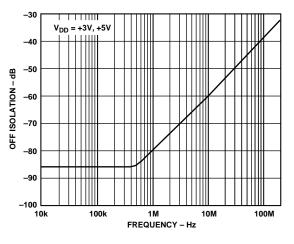


Figure 5. Off Isolation vs. Frequency

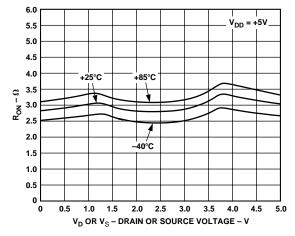


Figure 3. On Resistance as a Function of V_D (V_S) for Different Temperatures $V_{DD} = +5 \text{ V}$

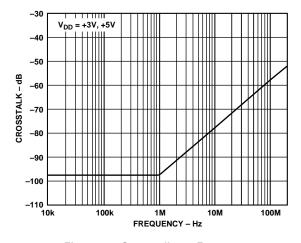


Figure 6. Crosstalk vs. Frequency

REV. 0 –5–

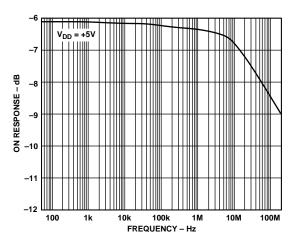
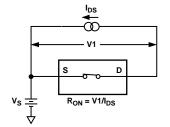
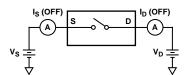


Figure 7. On Response vs. Frequency

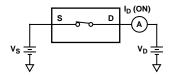
Test Circuits



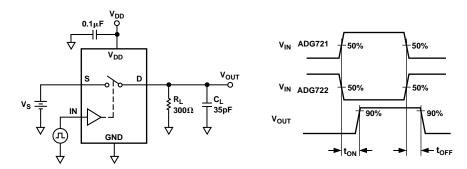
Test Circuit 1. On Resistance



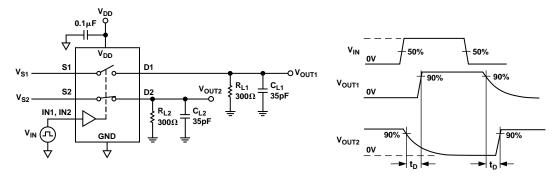
Test Circuit 2. Off Leakage



Test Circuit 3. On Leakage

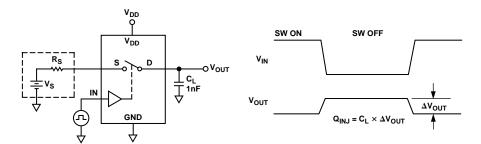


Test Circuit 4. Switching Times

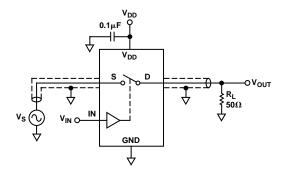


Test Circuit 5. Break-Before-Make Time Delay, t_D (ADG723 Only)

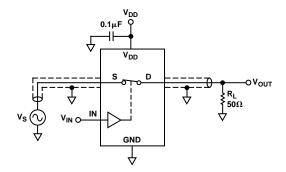
-6- REV. 0



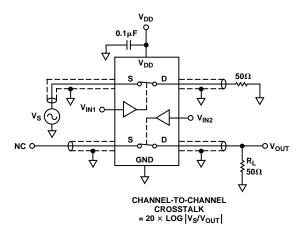
Test Circuit 6. Charge Injection



Test Circuit 7. Off Isolation



Test Circuit 9. Bandwidth



Test Circuit 8. Channel-to-Channel Crosstalk

REV. 0 -7-

APPLICATIONS INFORMATION

The ADG721/ADG722/ADG723 belongs to Analog Devices' new family of CMOS switches. This series of general purpose switches have improved switching times, lower on resistance, higher bandwidths, low power consumption and low leakage currents.

ADG721/ADG722/ADG723 Supply Voltages

Functionality of the ADG721/ADG722/ADG723 extends from +1.8 V to +5.5 V single supply, which makes it ideal for battery powered instruments, where important design parameters are power efficiency and performance.

It is important to note that the supply voltage effects the input signal range, the on resistance and the switching times of the part. By taking a look at the typical performance characteristics and the specifications, the effects of the power supplies can be clearly seen.

For V_{DD} = +1.8 V, on resistance is typically 40 Ω over the temperature range.

On Response vs. Frequency

Figure 8 illustrates the parasitic components that affect the ac performance of CMOS switches (the switch is shown surrounded by a box). Additional external capacitances will further degrade some performance. These capacitances affect feedthrough, crosstalk and system bandwidth.

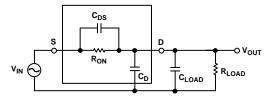


Figure 8. Switch Represented by Equivalent Parasitic Components

The transfer function that describes the equivalent diagram of the switch (Figure 8) is of the form (A)s shown below.

$$A(s) = R_T \left[\frac{s(R_{ON} \ C_{DS}) + 1}{s(R_{ON} \ C_T \ R_T) + 1} \right]$$

where:

$$C_T = C_{LOAD} + C_D + C_{DS}$$

$$R_T = R_{LOAD}/(R_{LOAD} + R_{ON})$$

The signal transfer characteristic is dependent on the switch channel capacitance, C_{DS} . This capacitance creates a frequency zero in the numerator of the transfer function A(s). Because the switch on resistance is small, this zero usually occurs at high frequencies. The bandwidth is a function of the switch output capacitance combined with C_{DS} and the load capacitance. The frequency pole corresponding to these capacitances appears in the denominator of A(s).

The dominant effect of the output capacitance, C_D, causes the pole breakpoint frequency to occur first. Therefore, in order to maximize bandwidth a switch must have a low input and output capacitance and low on resistance. The On Response vs. Frequency plot for the ADG721/ADG722/ADG723 can be seen in Figure 7.

Off Isolation

Off isolation is a measure of the input signal coupled through an off switch to the switch output. The capacitance, C_{DS} , couples the input signal to the output load, when the switch is off as shown in Figure 9.

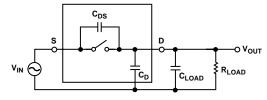


Figure 9. Off Isolation Is Affected by External Load Resistance and Capacitance

The larger the value of C_{DS} , larger values of feedthrough will be produced. The typical performance characteristic graph of Figure 5 illustrates the drop in off isolation as a function of frequency. From dc to roughly 1 MHz, the switch shows better than -80 dB isolation. Up to frequencies of 10 MHz, the off isolation remains better than -60 dB. As the frequency increases, more and more of the input signal is coupled through to the output. Off isolation can be maximized by choosing a switch with the smallest C_{DS} as possible. The values of load resistance and capacitance also affect off isolation, as they contribute to the coefficients of the poles and zeros in the transfer function of the switch when open.

$$A(s) = \left[\frac{s(R_{LOAD} C_{DS})}{s(R_{LOAD})(C_{LOAD} + C_D + C_{DS}) + 1}\right]$$

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

8-Lead μSOIC (RM-8)

